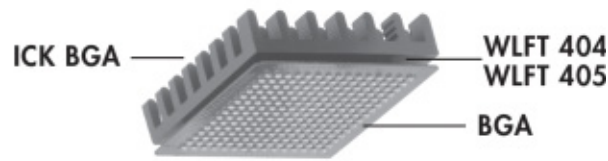


Heatsinks for BGAs


- particularly suited for **Ball Grid Arrays**
- heatsink dimensions match the respective BGA-type
- can be glued directly on the BGA component
- double-sided adhesive thermal conductive foil **WLF ...** → E 7
- **surface:** black anodised

art. no. ICK BGA 10 x 10 WLF ... 10 x 10		
art. no. ICK BGA 10 x 10 x 10 WLF ... 10 x 10		
art. no. ICK BGA 14 x 14 WLF ... 14 x 14		
art. no. ICK BGA 14 x 14 x 10 WLF ... 14 x 14		

Heatsinks for BGAs

<p>art. no.</p> <p>ICK BGA 21 x 21 WLF ... 21 x 21</p>		
<p>art. no.</p> <p>ICK BGA 23 x 23 WLF ... 23 x 23</p>		
<p>art. no.</p> <p>ICK BGA 23 x 23 x 10 WLF ... 23 x 23</p>		
<p>art. no.</p> <p>ICK BGA 27 x 27 WLF ... 27 x 27</p>		
<p>art. no.</p> <p>ICK BGA 27 x 27 x 10 WLF ... 27 x 27</p>		
<p>art. no.</p> <p>ICK BGA 27 x 27 x 14 WLF ... 27 x 27</p>		

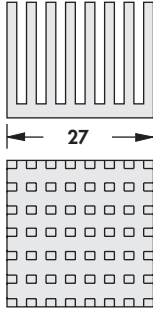
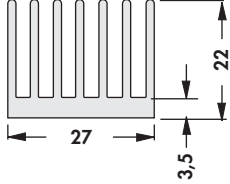
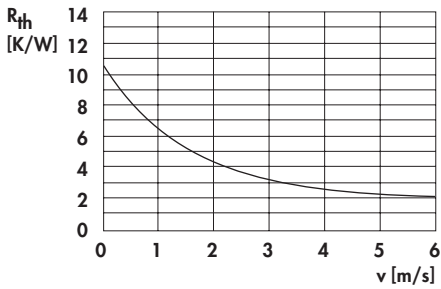
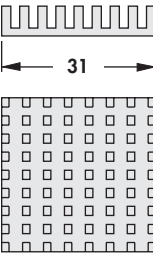
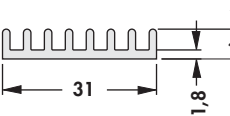
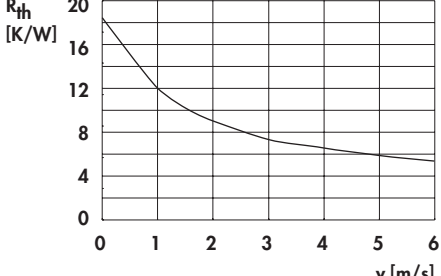
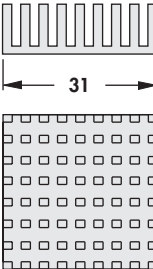
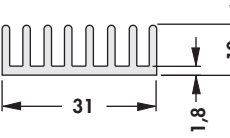
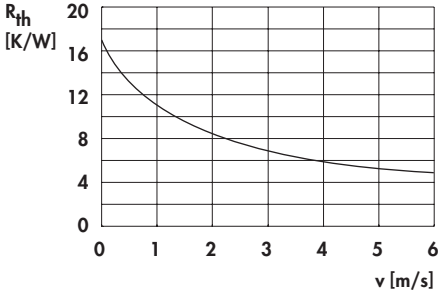
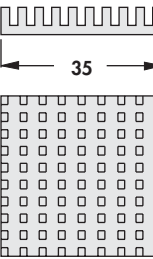
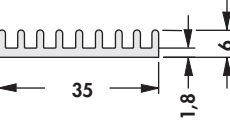
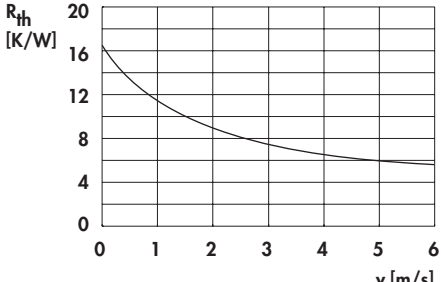
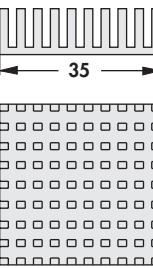
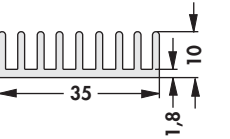
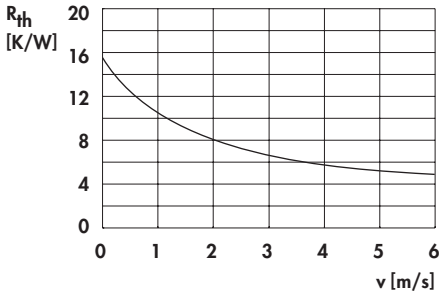
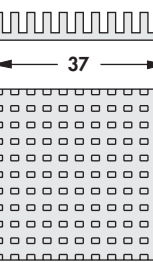
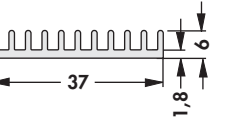
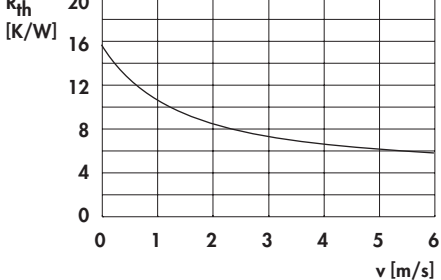
Mounts
SMD-heatsinks
Thermally conductive foil
Thermal conductive paste

→ E 42 – 46
→ B 45 – 47
→ E 5 – 13
→ E 19 – 20

Thermal conductive glue
Drilling pattern for Solid State Relais
Processor overview
Technical introduction

→ E 21 – 22
→ A 21
→ B 2 – 10
→ A 2 – 7

Heatsinks for BGAs

art. no. ICK BGA 27 x 27 x 22 WLF ... 27 x 27			
art. no. ICK BGA 31 x 31 WLF ... 31 x 31			
art. no. ICK BGA 31 x 31 x 10 WLF ... 31 x 31			
art. no. ICK BGA 35 x 35 WLF ... 35 x 35			
art. no. ICK BGA 35 x 35 x 10 WLF ... 35 x 35			
art. no. ICK BGA 37 x 37 x 6 WLF ... 37 x 37			

Heatsinks for BGAs

<p>art. no.</p> <p>ICK BGA 37 x 37 x 10 WLF ... 37 x 37</p>		
<p>art. no.</p> <p>ICK BGA 40 x 40 WLF ... 40 x 40</p>		
<p>art. no.</p> <p>ICK BGA 40 x 40 x 10 WLF ... 40 x 40</p>		
<p>art. no.</p> <p>ICK BGA 42,5 x 45 WLF ... 42,5 x 45</p>		

Mounts
SMD-heatsinks
Thermally conductive foil
Thermal conductive paste

→ E 42 – 46
→ B 45 – 47
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